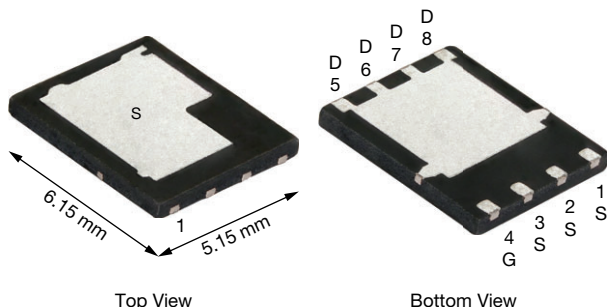


N-Channel 60 V (D-S) 175 °C MOSFET

PowerPAK® SO-8DC


FEATURES

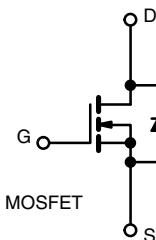
- TrenchFET® Gen IV power MOSFET
- Very low $R_{DS(on)}$ - Q_g figure of merit (FOM)
- Tuned for the lowest $R_{DS(on)}$ - Q_{oss} FOM
- 100 % R_g and UIS tested
- Top side cooling feature provides additional venue for thermal transfer
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converter
- Solar micro inverter
- Motor drive switch
- Battery and load switch
- Industrial



N-Channel MOSFET

PRODUCT SUMMARY

| | |
|----------------------------------------------------|---------|
| V_{DS} (V) | 60 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V | 0.00174 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5$ V | 0.0021 |
| Q_g typ. (nC) | 51 |
| I_D (A) ^a | 227 |
| Configuration | Single |

ORDERING INFORMATION

| | |
|---------------------------------|------------------|
| Package | PowerPAK® SO-8DC |
| Lead (Pb)-free and halogen-free | SiDR626EP-T1-RE3 |

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|--------------------------------------------------------------|----------------|---------------|----------------------|
| Drain-source voltage | V_{DS} | 60 | V |
| Gate-source voltage | V_{GS} | ± 20 | V |
| Continuous drain current ($T_J = 150$ °C) | I_D | $T_C = 25$ °C | 227 |
| | | $T_C = 70$ °C | 190 |
| | | $T_A = 25$ °C | 50.8 ^{b, c} |
| | | $T_A = 70$ °C | 42.5 ^{b, c} |
| Pulsed drain current ($t = 100$ μ s) | I_{DM} | 400 | A |
| Continuous source-drain diode current | I_S | $T_C = 25$ °C | 136 |
| | | $T_A = 25$ °C | 6.8 ^{b, c} |
| Single pulse avalanche current | I_{AS} | 50 | |
| Single pulse avalanche energy | E_{AS} | 125 | mJ |
| Maximum power dissipation | P_D | $T_C = 25$ °C | 150 |
| | | $T_C = 70$ °C | 105 |
| | | $T_A = 25$ °C | 7.5 ^{b, c} |
| | | $T_A = 70$ °C | 5.25 ^{b, c} |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +175 | °C |
| Soldering recommendations (peak temperature) ^{d, e} | | 260 | |

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

**THERMAL RESISTANCE RATINGS**

| PARAMETER | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
|------------------------------------------|---------------|------------|---------|---------|------|
| Maximum junction to ambient ^a | $t \leq 10$ s | R_{thJA} | 15 | 20 | °C/W |
| Maximum junction to case (drain) | Steady state | R_{thJC} | 0.8 | 1 | |
| Maximum junction to case (source) | Steady state | R_{thJC} | 1.1 | 1.4 | |

Notes

a. Surface mounted on 1" x 1" FR4 board

SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------------------------------------------|--------------------------------------|--------------------------------------------------------------------------------------------------------------------------|------|---------|---------|-------|
| Static | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | - | - | V |
| V _{DS} temperature coefficient | ΔV _{DS} /T _J | I _D = 10 mA | - | 33 | - | mV/°C |
| V _{GS(th)} temperature coefficient | ΔV _{GS(th)} /T _J | I _D = 250 μA | - | -8.8 | - | |
| Gate-source threshold voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 2 | - | 4 | V |
| Gate-source leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 20 V | - | - | 100 | nA |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V | - | - | 1 | μA |
| | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 70 °C | - | - | 15 | |
| Drain-source on-state resistance ^a | R _{DS(on)} | V _{GS} = 10 V, I _D = 20 A | - | 0.00145 | 0.00174 | Ω |
| | | V _{GS} = 7.5 V, I _D = 20 A | - | 0.00175 | 0.0021 | |
| Forward transconductance ^a | g _{fs} | V _{DS} = 15 V, I _D = 20 A | - | 78 | - | S |
| Dynamic ^b | | | | | | |
| Input capacitance | C _{iss} | V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz | - | 5130 | - | pF |
| Output capacitance | C _{oss} | | - | 1190 | - | |
| Reverse transfer capacitance | C _{rss} | | - | 39 | - | |
| Total gate charge | Q _g | V _{DS} = 30 V, V _{GS} = 10 V, I _D = 20 A | - | 68 | 102 | nC |
| Gate-source charge | Q _{gs} | V _{DS} = 30 V, V _{GS} = 7.5 V, I _D = 20 A | - | 51 | 77 | |
| Gate-drain charge | Q _{gd} | | - | 25 | - | |
| Output charge | Q _{oss} | | - | 7.4 | - | |
| Gate resistance | R _g | V _{DS} = 30 V, V _{GS} = 0 V | - | 71 | - | |
| Turn-on delay time | t _{d(on)} | f = 1 MHz | 0.2 | 0.62 | 1.1 | Ω |
| Rise time | t _r | V _{DD} = 30 V, R _L = 1.5 Ω, I _D ≅ 20 A, V _{GEN} = 10 V, R _g = 1 Ω | - | 20 | 40 | ns |
| Turn-off delay time | t _{d(off)} | | - | 10 | 20 | |
| Fall time | t _f | | - | 35 | 70 | |
| Turn-on delay time | t _{d(on)} | | - | 7 | 14 | |
| Rise time | t _r | V _{DD} = 30 V, R _L = 1.5 Ω, I _D ≅ 20 A, V _{GEN} = 7.5 V, R _g = 1 Ω | - | 24 | 48 | |
| Turn-off delay time | t _{d(off)} | | - | 25 | 50 | |
| Fall time | t _f | | - | 30 | 60 | |
| | | | - | 10 | 20 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous source-drain diode current | I _S | T _C = 25 °C | - | - | 136 | A |
| Pulse diode forward current | I _{SM} | | - | - | 400 | |
| Body diode voltage | V _{SD} | I _S = 5 A, V _{GS} = 0 V | - | 0.74 | 1.1 | V |
| Body diode reverse recovery time | t _{rr} | I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C | - | 45 | 90 | ns |
| Body diode reverse recovery charge | Q _{rr} | | - | 45 | 90 | nC |
| Reverse recovery fall time | t _a | | - | 21 | - | ns |
| Reverse recovery rise time | t _b | | - | 24 | - | |

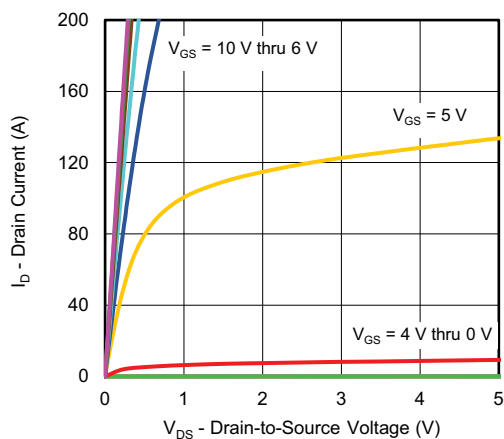
Notesa. Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %

b. Guaranteed by design, not subject to production testing

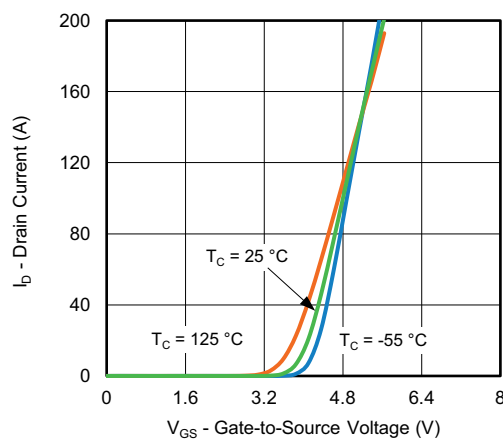
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



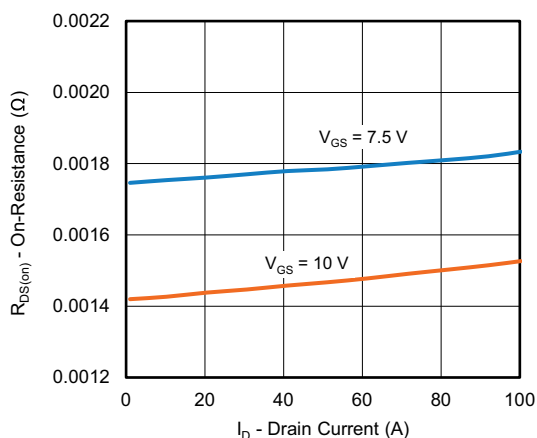
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



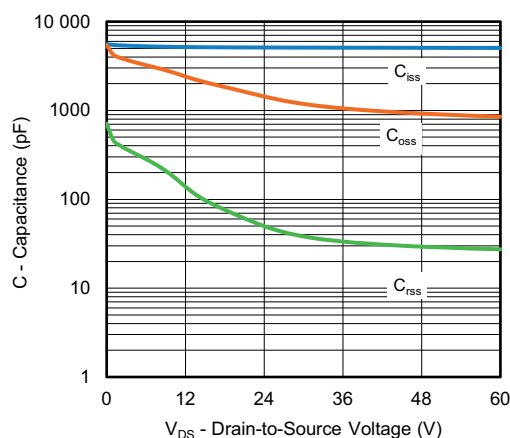
Output Characteristics



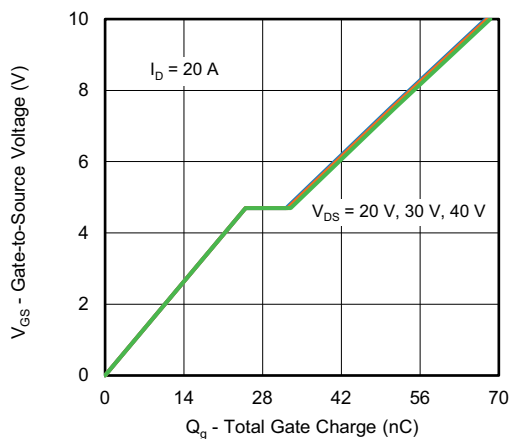
Transfer Characteristics



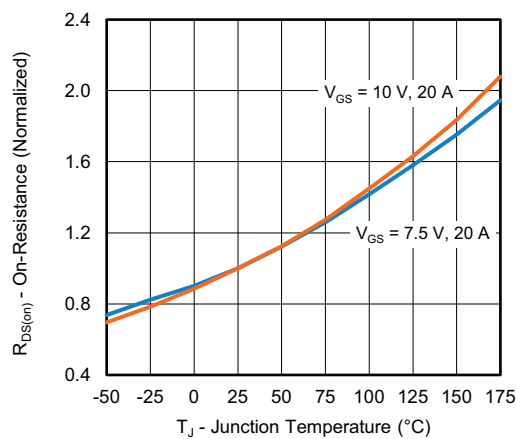
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



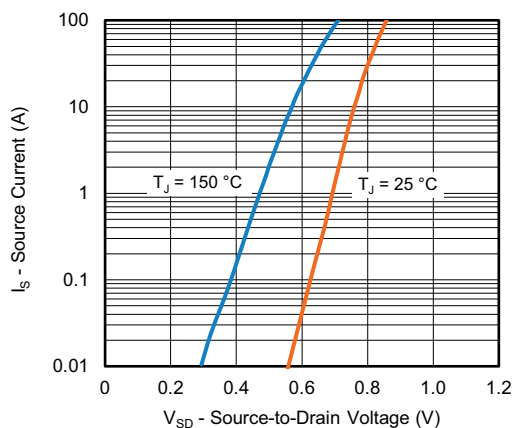
Gate Charge



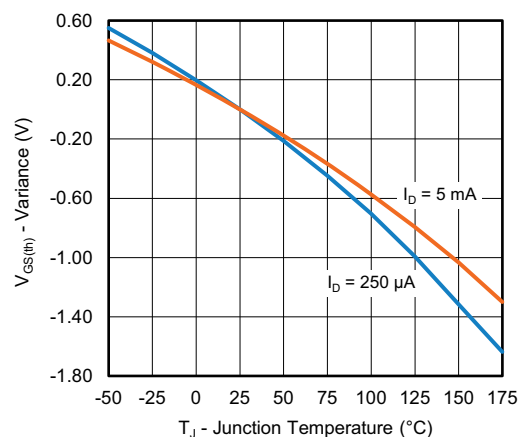
On-Resistance vs. Junction Temperature



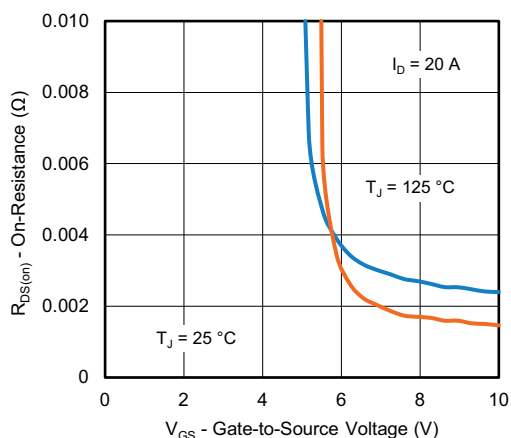
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



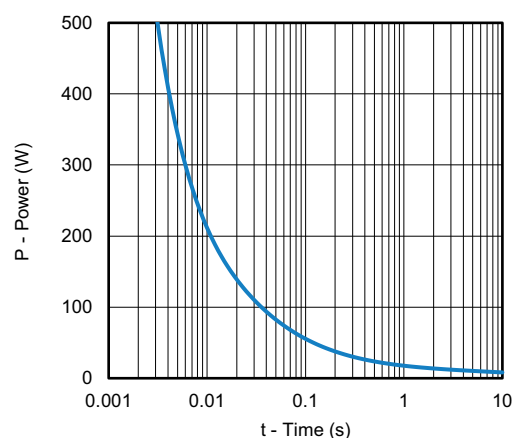
Source-Drain Diode Forward Voltage



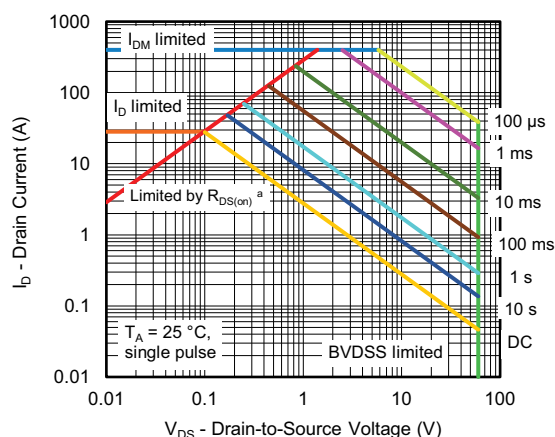
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



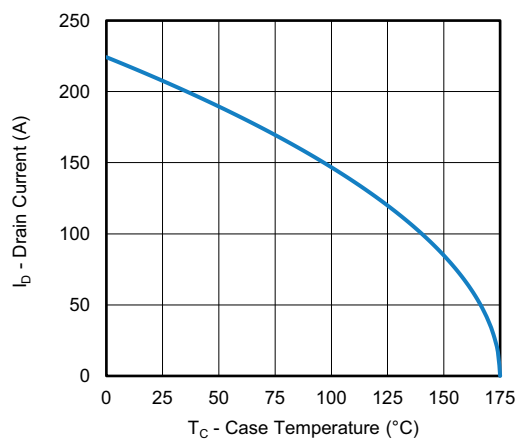
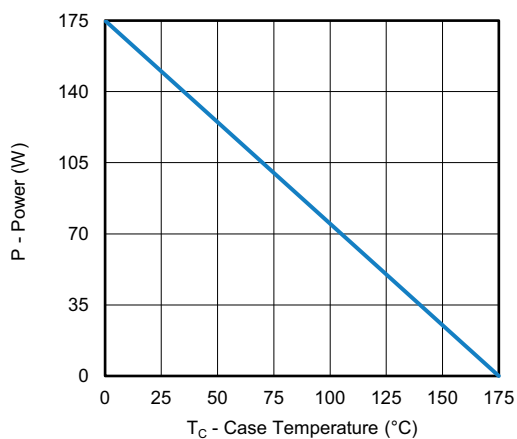
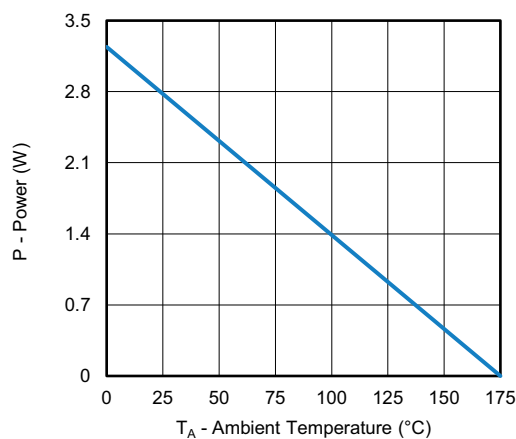
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

Note

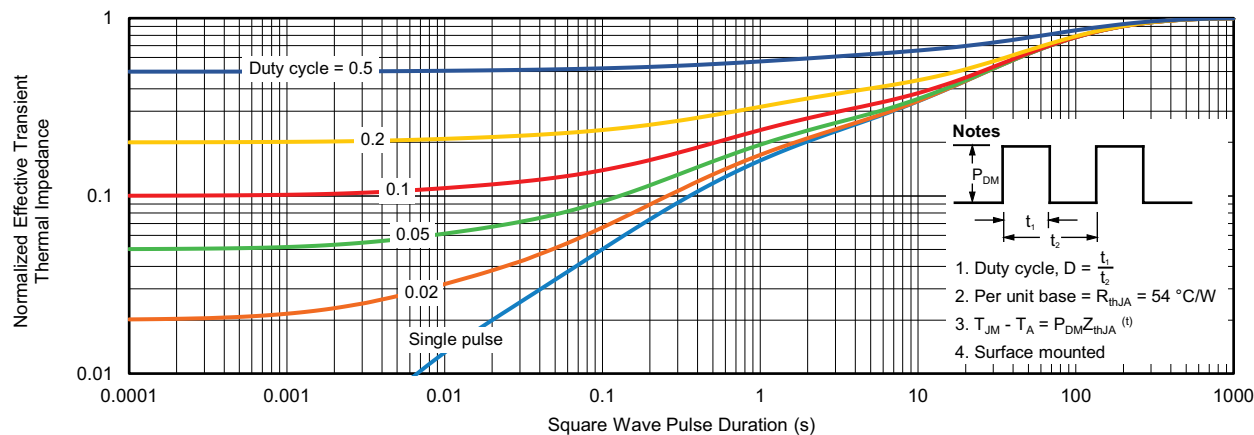
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case

Power, Junction-to-Ambient
Note

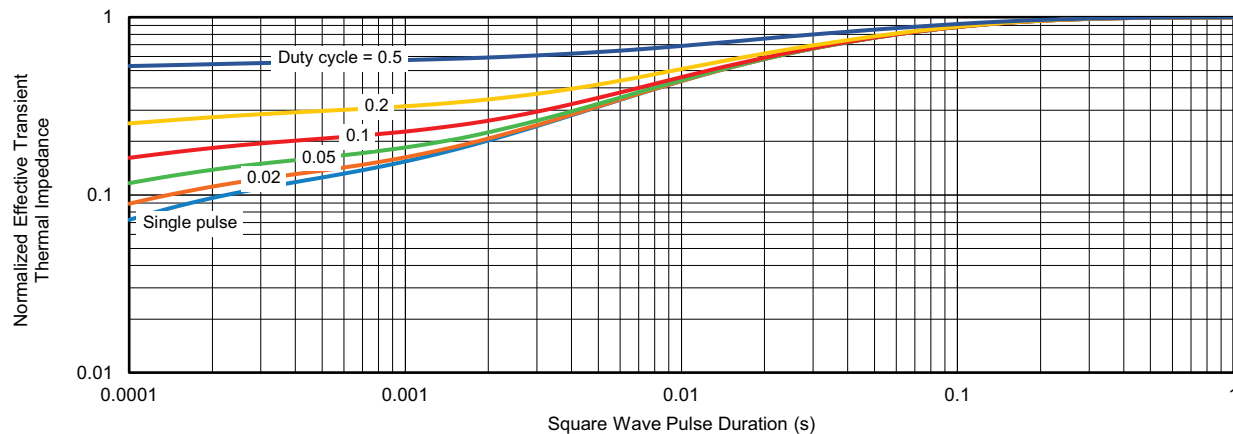
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

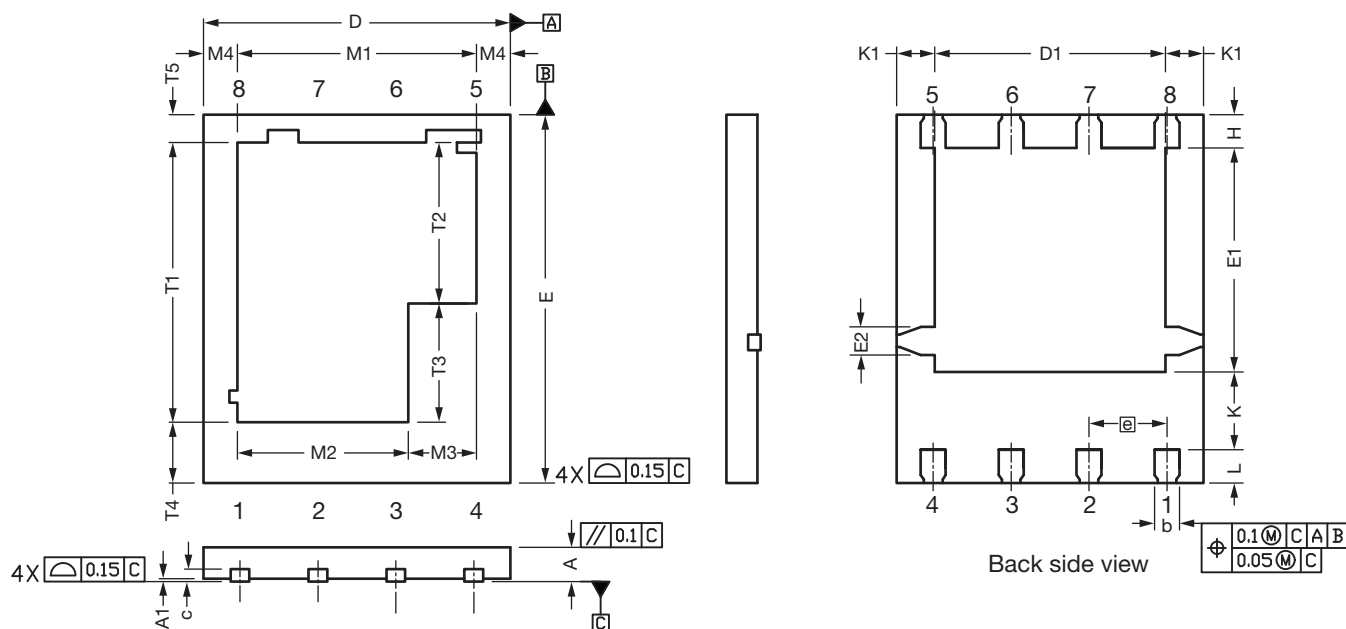


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62063.



PowerPAK® SO-8 Double Cooling Case Outline



| DIM. | MILLIMETERS | | | INCHES | | |
|-----------------------------------|-------------|------|------|------------|-------|-------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.51 | 0.56 | 0.61 | 0.020 | 0.022 | 0.024 |
| A1 | 0.00 | 0.02 | 0.05 | 0.000 | 0.001 | 0.002 |
| b | 0.36 | 0.41 | 0.46 | 0.014 | 0.016 | 0.018 |
| c | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| D | 4.90 | 5.00 | 5.10 | 0.193 | 0.197 | 0.201 |
| D1 | 3.71 | 3.76 | 3.81 | 0.146 | 0.148 | 0.150 |
| e | 1.27 BSC | | | 0.050 BSC | | |
| E | 5.90 | 6.00 | 6.10 | 0.232 | 0.236 | 0.240 |
| E1 | 3.60 | 3.65 | 3.70 | 0.142 | 0.144 | 0.146 |
| E2 | 0.46 typ. | | | 0.018 typ. | | |
| H | 0.49 | 0.54 | 0.59 | 0.019 | 0.021 | 0.023 |
| K | 1.22 | 1.27 | 1.32 | 0.048 | 0.050 | 0.052 |
| K1 | 0.64 typ. | | | 0.025 typ. | | |
| L | 0.49 | 0.54 | 0.59 | 0.019 | 0.021 | 0.023 |
| M1 | 3.8 | 3.90 | 4.00 | 0.150 | 0.154 | 0.158 |
| M2 | 2.69 | 2.79 | 2.89 | 0.106 | 0.110 | 0.114 |
| M3 | 1.01 | 1.11 | 1.21 | 0.040 | 0.044 | 0.048 |
| M4 | 0.56 typ. | | | 0.022 typ. | | |
| N | 8 | | | 8 | | |
| T1 | 4.46 | 4.56 | 4.66 | 0.176 | 0.180 | 0.184 |
| T2 | 2.53 | 2.63 | 2.73 | 0.100 | 0.104 | 0.108 |
| T3 | 1.83 | 1.93 | 2.03 | 0.072 | 0.076 | 0.080 |
| T4 | 0.97 typ. | | | 0.038 typ. | | |
| T5 | 0.48 typ. | | | 0.019 typ. | | |
| ECN: T24-0304-Rev. C, 29-Jul-2024 | | | | | | |
| DWG: 6048 | | | | | | |

RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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